L Number	Hits	Search Text	DB	Time stamp
3	1	4423701.pn.	USPAT;	2003/03/04 10:10
4	1	4423701.pn. and (heater or temperature)	US-PGPUB USPAT;	2003/03/04 11:13
			US-PGPUB	
5	9	(USPAT;	2003/03/04 13:26
		US-5916365-\$ or US-5292554-\$ or	US-PGPUB	
		US-4423701-\$ or US-4664939-\$).did. or (US-20020197863-\$ or US-20020076490-\$ or		
		US-20020197803-\$ 01 03-20020078490-\$ 01 US-20020056414-\$).did.		
6	2	, ,	USPAT;	2003/03/04 13:51
		US-5916365-\$ or US-5292554-\$ or	US-PGPUB	
		US-4423701-\$ or US-4664939-\$).did. or		
		(US-20020197863-\$ or US-20020076490-\$ or		
7	0	US-20020056414-\$).did.) and aperture 4423701.pn. and gase	USPAT;	2003/03/04 13:51
'	0	4425701.pm. and gase	US-PGPUB	2003/03/04 13.31
8	1	4423701.pn. and gas	USPAT;	2003/03/04 13:51
1			US-PGPUB	
11	1	4664939.pn. and gas	USPAT;	2003/03/04 14:09
14	2	((US-6524952-\$ or US-6387185-\$ or	US-PGPUB	2002/02/04 14.19
**	2	US-5916365-\$ or US-5292554-\$ or	USPAT; US-PGPUB	2003/03/04 14:18
		US-4423701-\$ or US-4664939-\$).did. or	35 23102	
		(US-20020197863-\$ or US-20020076490-\$ or		
15	0	US-20020056414-\$).did.) and electrostatic ((US-6524952-\$ or US-6387185-\$ or	Hanna.	2002/02/04 14 12
15	U	US-5916365-\$ or US-5292554-\$ or	USPAT; US-PGPUB	2003/03/04 14:18
		US-4423701-\$ or US-4664939-\$).did. or	05 10105	
		(US-20020197863-\$ or US-20020076490-\$ or	}	
	10	US-20020056414-\$).did.) and piston		
16	18	atomic adj layer adj deposition and piston	USPAT;	2003/03/04 14:22
17	437	deposition and chamber and support and	US-PGPUB USPAT;	2003/03/04 14:23
	10,	wafer and piston	US-PGPUB	2003/03/04 14:23
18	242	(deposition and chamber and support and	USPAT;	2003/03/04 14:23
19	1.01	wafer and piston) and region and gas	US-PGPUB	0000/00/04 14 05
19	191	((deposition and chamber and support and wafer and piston) and region and gas) and	USPAT; US-PGPUB	2003/03/04 14:25
		@ad<=20010727	OS TOTOB	
20	94		USPAT;	2003/03/04 14:25
21	0.3	piston	US-PGPUB	0000/00/04 14 06
21	83	(deposition and wafer adj support and piston) and @ad<=20010727	USPAT; US-PGPUB	2003/03/04 14:26
22	8	((deposition and wafer adj support and	USPAT;	2003/03/04 14:28
		piston) and @ad<=20010727) and wafer adj	US-PGPUB	
	_	support with piston		
23	1	5228502.pn.	USPAT;	2003/03/04 14:28
_	498	atomic adj layer adj deposition	US-PGPUB USPAT;	2003/03/03 14:05
			US-PGPUB	2333, 33, 33 14.03
-	194	(atomic adj layer adj deposition) and	USPAT;	2003/02/27 15:50
_	94	chamber and region\$1	US-PGPUB	2002/02/27 16:42
-	94	((atomic adj layer adj deposition) and chamber and region\$1) and @ad<=20010727	USPAT; US-PGPUB	2003/02/27 16:43
-	67	(((atomic adj layer adj deposition) and	USPAT;	2003/02/27 15:51
		chamber and region\$1) and @ad<=20010727)	US-PGPUB	
	1.0	and wafer	HODAE	0000/00/05 15 55
-	16	((((atomic adj layer adj deposition) and chamber and region\$1) and @ad<=20010727)	USPAT; US-PGPUB	2003/02/27 15:51
		and wafer) and support	OD EGEOD	
-	12	(((((atomic adj layer adj deposition) and	USPAT;	2003/02/27 16:01
		chamber and region\$1) and @ad<=20010727)	US-PGPUB	
_	1	and wafer) and support) and heater 5951776.pn.	HCDAT.	2002/02/27 16:06
	1	0001/70.pii.	USPAT; US-PGPUB	2003/02/27 16:06
-	1	6525747.pn.	USPAT;	2003/02/27 16:40
	_	W.C.1.7.400.5.W. The	US-PGPUB	
-	1	"6174805".PN.	USPAT;	2003/02/27 16:36
	7		US-PGPUB	

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_	1	"6132514".PN.	USPAT;	2003/02/27 16:36
_	1	"6071552".PN.	US-PGPUB USPAT; US-PGPUB	2003/02/27 16:37
-	1	"5998871".PN.	USPAT; US-PGPUB	2003/02/27 16:37
_	1	"5998871".PN.	USPAT; US-PGPUB	2003/02/27 16:37
-	1	"5972785".PN.	USPAT; US-PGPUB	2003/02/27 16:37
_	1	"5916365".PN.	USPAT; US-PGPUB	2003/02/27 16:37
_	1	"5416045".PN.	USPAT; US-PGPUB	2003/02/27 16:38
-	1	"5344792".PN.	USPAT; US-PGPUB	2003/02/27 16:38
-	1	"6190732".PN.	USPAT; US-PGPUB	2003/02/27 16:39
_	1	"6174377".PN.	USPAT; US-PGPUB	2003/02/27 16:39
_	1	"5935338".PN.	USPAT; US-PGPUB	2003/02/27 16:40
_	1	"5879459".PN.	USPAT; US-PGPUB	2003/02/27 16:40
_	1	"5582866".PN.	USPAT; US-PGPUB	2003/02/27 16:40
_	655	700/121.ccls.	USPAT; US-PGPUB	2003/02/27 16:40
_	213	700/121.ccls. and deposition	USPAT; US-PGPUB	2003/02/27 16:41
_	113	(700/121.ccls. and deposition) and chamber	USPAT; US-PGPUB	2003/02/27 16:41
_	90	((700/121.ccls. and deposition) and chamber) and @ad<=20010727	USPAT; US-PGPUB	2003/03/03 14:47
_	3	(((700/121.ccls. and deposition) and chamber) and @ad<=20010727) and piston	USPAT; US-PGPUB	2003/02/27 16:41
_	1	(((atomic adj layer adj deposition) and chamber and region\$1) and @ad<=20010727) and piston	USPAT; US-PGPUB	2003/02/27 16:50
-	1228	118/719.ccls.	USPAT; US-PGPUB	2003/02/27 16:50
-	55	118/719.ccls. and wafer and piston	USPAT; US-PGPUB	2003/02/27 16:50
-	16	(118/719.ccls. and wafer and piston) and aperture	USPAT; US-PGPUB	2003/02/27 16:51
-	15	kosowski.xa.	USPAT; US-PGPUB	2003/03/03 14:05
-	4183	deposition and wafer and support and chamber and region\$2 and temperature and two and gas	USPAT; US-PGPUB	2003/03/03 14:47
_	3626	(deposition and wafer and support and chamber and region\$2 and temperature and two and gas) and @ad<=20010727	USPAT; US-PGPUB	2003/03/03 17:34
_	167	((deposition and wafer and support and chamber and region\$2 and temperature and	USPAT; US-PGPUB	2003/03/03 14:50
_	11	two and gas) and @ad<=20010727) and piston (((deposition and wafer and support and chamber and region\$2 and temperature and two and gas) and @ad<=20010727) and piston) and monolayer	USPAT; US-PGPUB	2003/03/03 14:51
_	90	((deposition and wafer and support and chamber and region\$2 and temperature and two and gas) and @ad<=20010727) and atomic adj layer	USPAT; US-PGPUB	2003/03/03 14:51
_	1413684	(((deposition and wafer and support and chamber and region\$2 and temperature and two and gas) and @ad<=20010727) and atomic adj layer) and deposition near\$5 region\$1	USPAT; US-PGPUB	2003/03/03 14:53
			I	L

_	90	(((deposition and wafer and support and	USPAT;	2003/03/03 16:18
		chamber and region\$2 and temperature and	US-PGPUB	2003/03/03 10:18
	:	two and gas) and @ad<=20010727) and atomic	00 10102	
		adj layer) and (deposition near\$5		
		region\$1)		
<u> </u>	1	109101171	USPAT;	2003/03/03 15:11
	-		US-PGPUB	2003/03/03 13.11
_	1		USPAT;	2003/03/03 15:11
			US-PGPUB	2003/03/03 13:11
l _	1		USPAT;	2003/03/03 15:11
	1		USPAT; US-PGPUB	2003/03/03 15:11
_	1		USPAT:	2003/03/03 15:11
_	1			2003/03/03 15:11
	4	//damaaihiaa aad	US-PGPUB	2002/02/02 16:25
-	4	((deposition and wafer and support and	USPAT;	2003/03/03 16:35
		chamber and region\$2 and temperature and	US-PGPUB	
		two and gas) and @ad<=20010727) and		
	C.	moveable adj support		
_	64	deposition and moveable adj support	USPAT;	2003/03/03 16:35
			US-PGPUB	
_	62	(deposition and moveable adj support) and	USPAT;	2003/03/03 16:37
		@ad<=20010727	US-PGPUB	
-	25	((deposition and moveable adj support) and	USPAT;	2003/03/03 17:16
		@ad<=20010727) and wafer	US-PGPUB	
-	1		USPAT;	2003/03/03 16:45
			US-PGPUB	
-	1		USPAT;	2003/03/03 16:45
			US-PGPUB	
-	1		USPAT;	2003/03/03 16:46
			US-PGPUB	
_	1		USPAT;	2003/03/03 16:46
			US-PGPUB	
-	655	700/121.ccls.	USPAT;	2003/03/03 17:16
			US-PGPUB	
-	2	700/121.ccls. and atomic adj layer adj	USPAT;	2003/03/03 17:33
		deposition	US-PGPUB	
-	21	interconnected with deposition with	USPAT;	2003/03/03 17:33
		region\$2	US-PGPUB	
-	21	(interconnected with deposition with	USPAT;	2003/03/04 10:10
		region\$2) and @ad<=20010727	US-PGPUB	

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